



# SOT1870-1

Bumped die with 8 functional bumps; 2.51 mm x 2.51 mm x 0.16 mm

31 October 2017

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	WLCSP8
<b>Package type industry code</b>	WLCSP8
<b>Package style descriptive code</b>	WLCSP (wafer level chip-size package)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	4-10-2016
<b>Manufacturer package code</b>	SOT1870

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	-	-	2.51	-	mm
E	package width	-	-	2.51	-	mm
A <sub>2</sub>	package height	-	-	0.16	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	8	-	A/A



## 2. Package outline

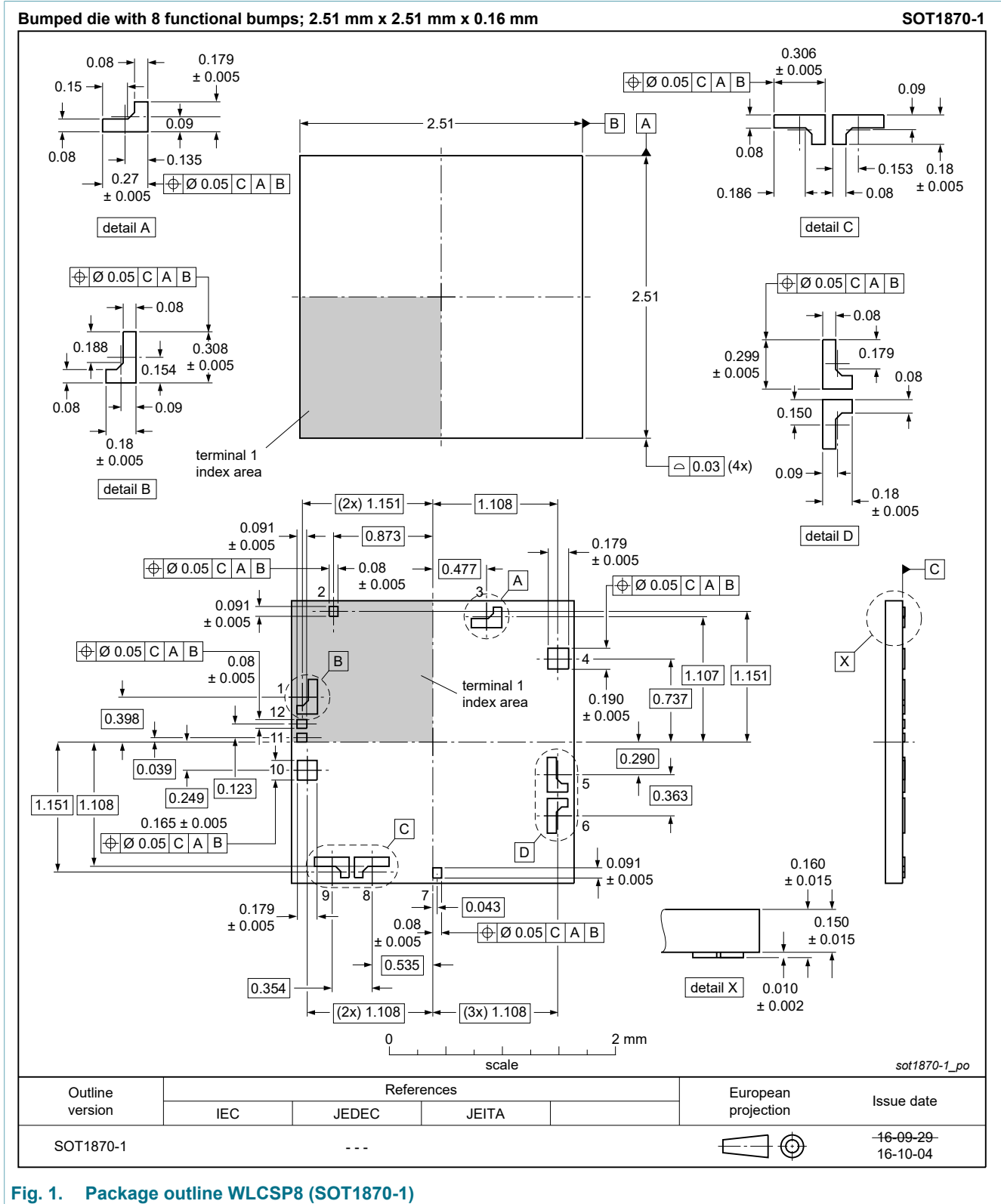


Fig. 1. Package outline WLCSP8 (SOT1870-1)

### 3. Legal information

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